


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	POWER AND DISCRETES/26/16459	
1.3 Title of PCI	Conversion from D7 Al-Mg wire to D7 soft Al wire in power fusion bonder on selected product (TO 252 DPAK/B553).	
1.4 Product Category	Pls refer to the impacted product list	
1.5 Issue date	2026-06-25	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Angelo RAO
2.1.2 Marketing Manager	Giuseppe BAZZANO
2.1.3 Quality Manager	Massimiliano CUOZZO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Alternate Source Supplier (supplier qualified)	SHENZEN

4. Description of change

	Old	New
4.1 Description	Ametek D7 Al-Mg wire.	Ametek D7 soft Al wire.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Processability	

5. Reason / motivation for change

5.1 Motivation	Ametek Al-Mg will stop supply STS.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	by QA number
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7. Timing / schedule

7.1 Date of qualification results	2026-05-26
7.2 Intended start of delivery	2026-07-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16459 STS-DPAK- AL-Mg wire to soft Al wire with Powerfusion for B553.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-06-25

9. Attachments (additional documentations)

16459 Public product.pdf
 16459 STS-DPAK- AL-Mg wire to soft Al wire with Powerfusion for B553.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	MJD44H11T4-A	

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